



Features

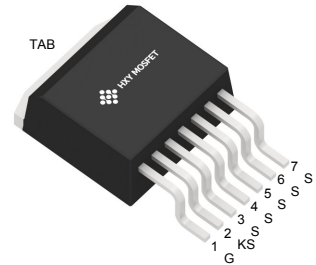
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Avalanche Ruggednes

Applications

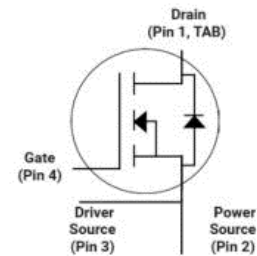
- Solar Inverters
- Switch Mode Power Supplies
- Auxiliary power supplies
- Smart meters



Ordering Part Number	Package	Brand
HXYS6N170T6	TO-263-7L	HXY MOSFET



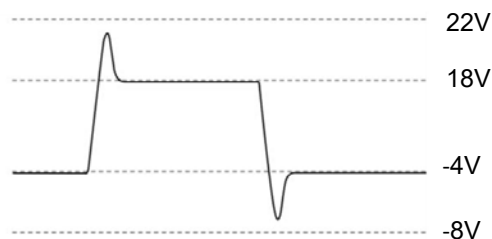
TO-263-7L



Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	1700	V
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	6.7 5	A
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{D\text{ pulse}}$	16.7	A
Avalanche energy, single pulse ($L=10\text{mH}$)	E_{AS}	90	mJ
Gate-Source voltage	V_{GS}	-4/+18	V
Gate-Source voltage (Absolute maximum values)	V_{GSmax}	-8/+22	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	86	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+175	$^\circ\text{C}$

•Example of acceptable V_{GS} waveform





Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	R_{thJC}	1.7	°C/W
Thermal resistance, junction – ambient. Max	R_{thJA}	40	

Electrical Characteristic (at $T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Drain-source breakdown voltage	BV _{DSS}	1700	-	-	V	V _{GS} =0V, I _D =100uA
Gate threshold voltage	V _{GS(th)}	1.8	3	4.5	V	V _{DS} =V _{GS} ,I _D =380uA
Zero gate voltage drain current	I _{DSS}	-	1	10	μA	V _{DS} =1700V,V _{GS} =0V
		-	5	-		T _C =25°C T _C =175°C
Gate-source leakage current	I _{GSS}	-		100	nA	V _{GS} =20V,V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	700	910	mΩ	V _{GS} =18V, I _D =1A,
		-	1280	-		T _J =25°C T _J =175°C
Input Capacitance	C _{iss}	-	285	-	pF	V _{DS} = 1000V V _{GS} = 0V T _J = 25°C V _{AC} = 25mV f = 1MHz
Output Capacitance	C _{oss}	-	15.3	-		
Reverse Transfer Capacitance	C _{rss}	-	2.2	-		
Gate Total Charge	Q _G	-	16.5	-	nC	V _{DS} = 1000V V _{GS} = -5/18V I _D = 1A
Gate-Source charge	Q _{gs}	-	2.7	-		
Gate-Drain charge	Q _{gd}	-	12.5	-		
Turn-On Switching Energy	E _{ON}	-	73.9	-	μJ	V _{DD} = 1000V V _{GS} = -3.5/+18V I _D = 2A R _G = 10Ω L = 1880uH
Turn-Off Switching Energy	E _{OFF}	-	20.4	-		
Turn-on delay time	t _{d(on)}	-	6.2	-	ns	
Rise time	t _r	-	13.7	-		
Turn-off delay time	t _{d(off)}	-	9.4	-		
Fall time	t _f	-	45.4	-		
Gate resistance	R _G	-	18.0	-	Ω	V _{AC} = 25mV, f=1MHz
Body Diode Forward Voltage	V _{SD}		4		V	V _{GS} =0V,I _{SD} =1A, T _J =25°C
			3.8			V _{GS} =0V,I _{SD} =1A, T _J =175°C
Body Diode Reverse Recovery Time	t _{rr}	-	33.5	-	ns	V _R = 1000V, V _{GS} = -3.5V/+18V I _D = 2A,Rg=30Ω di/dt =1000A/μS L=1880uH
Body Diode Reverse Recovery Charge	Q _{rr}	-	56.1	-	nC	



Typical Performance Characteristics

Fig 1. Output Characteristic ($T_J = -55^\circ\text{C}$)

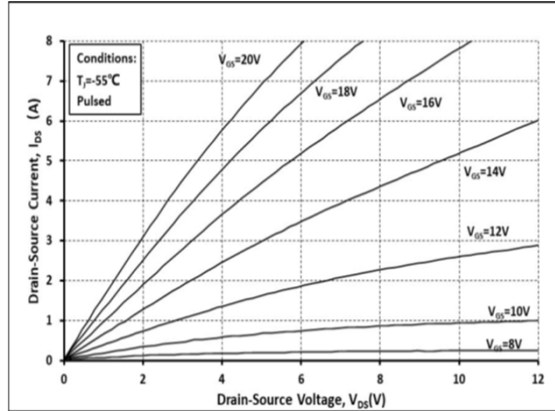


Fig 2. Output Characteristic ($T_J = 25^\circ\text{C}$)

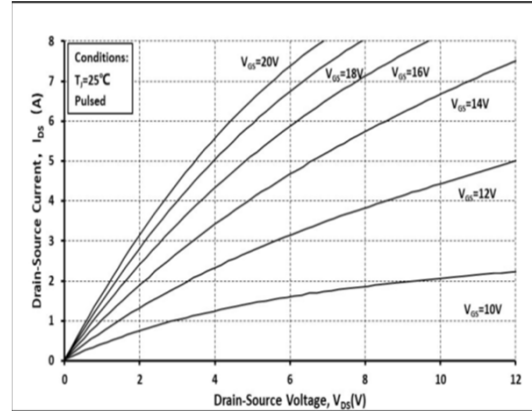


Fig 3. Output Characteristic ($T_J = 175^\circ\text{C}$)

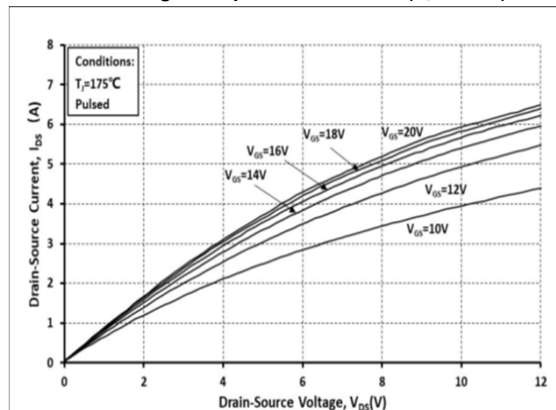


Fig 4: $R_{DS(on)}$ Vs I_{DS} Characteristic

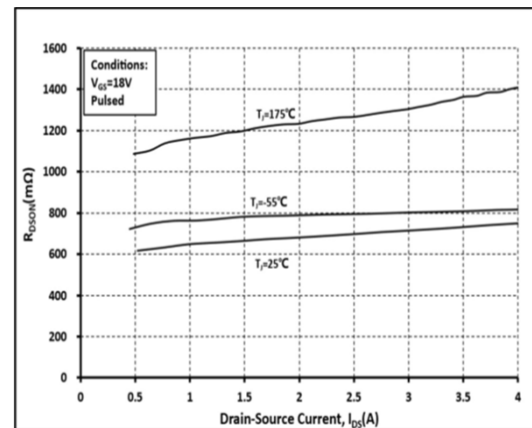


Fig 5: $R_{DS(on)}$ vs. Temperature

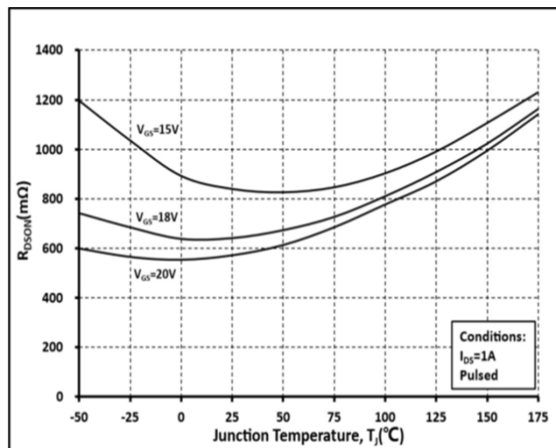


Fig 6: Transfer Characteristic

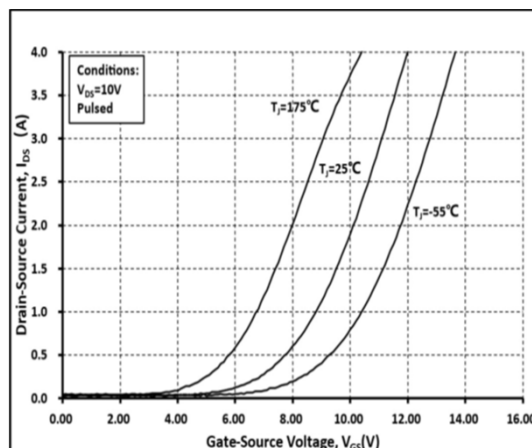




Fig 7: Body-diode Characteristic ($T_J = -55^\circ\text{C}$)

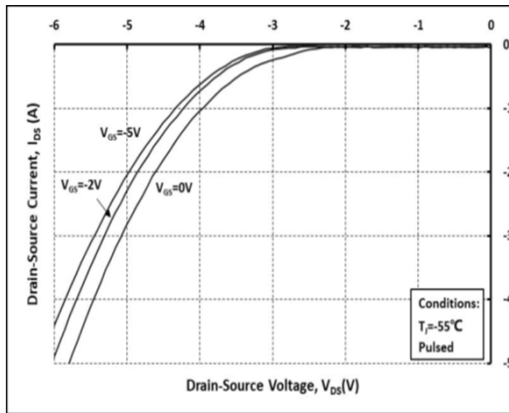


Fig 8: Body-diode Characteristic ($T_J = 25^\circ\text{C}$)

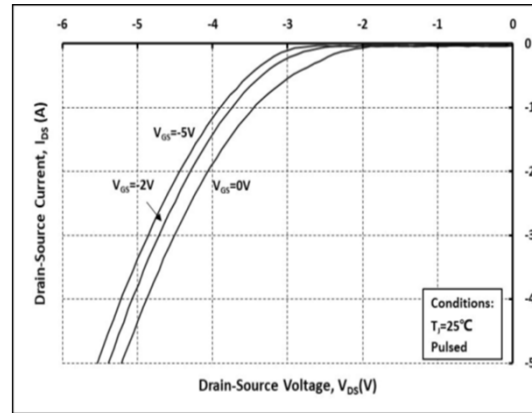


Fig 9: Body-diode Characteristic ($T_J = 175^\circ\text{C}$)

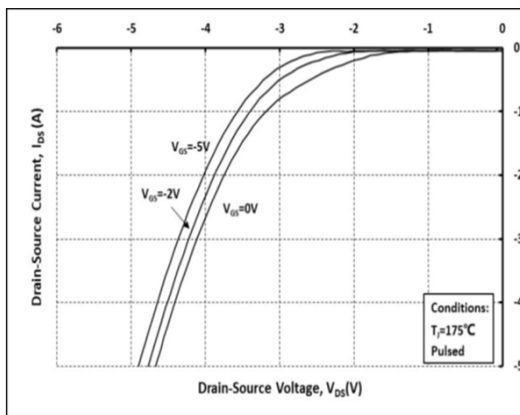


Fig 10: V_{TH} Vs T_J Temperature Characteristic

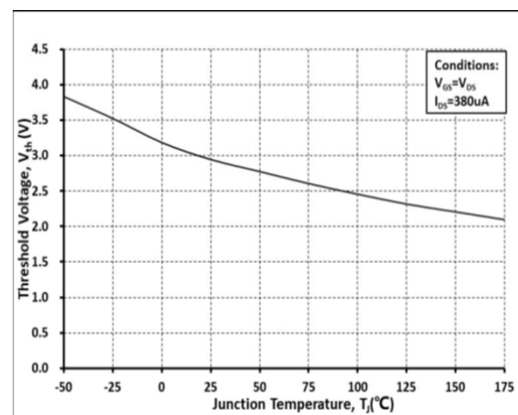


Fig 11: Gate Charge Characteristics

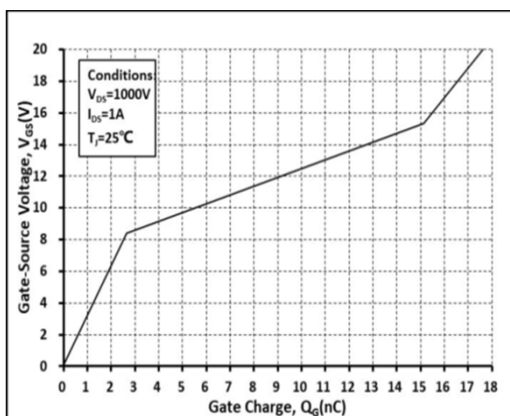


Fig 12: 3rd Quadrant Characteristic ($T_J = -55^\circ\text{C}$)

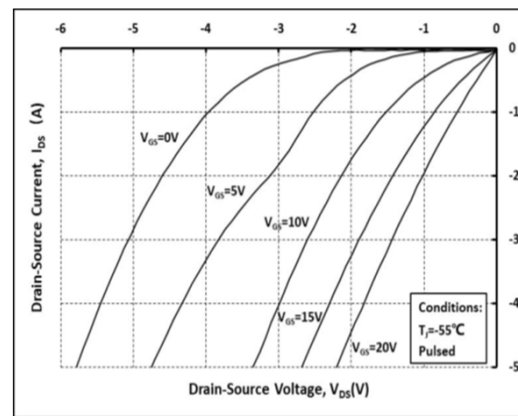




Fig 13: 3rd Quadrant Characteristic($T_J=25^{\circ}\text{C}$)

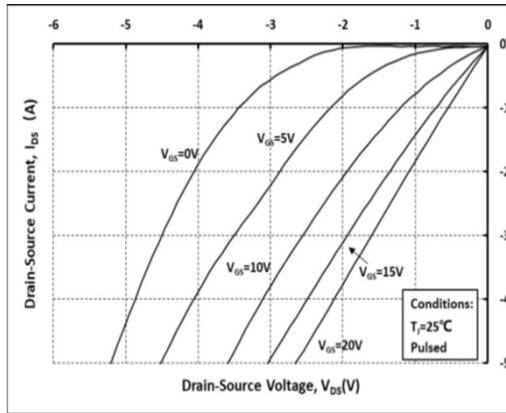


Fig 14: 3rd Quadrant Characteristic($T_J=175^{\circ}\text{C}$)

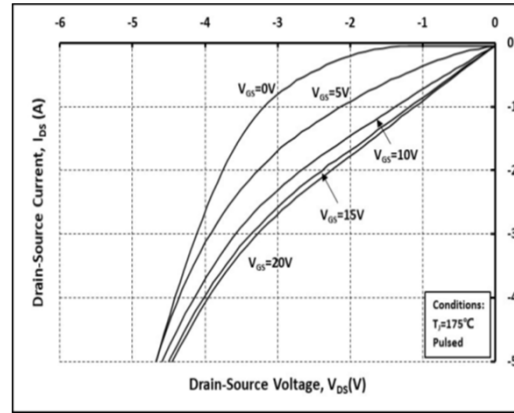


Fig 15: Capacitance Characteristic

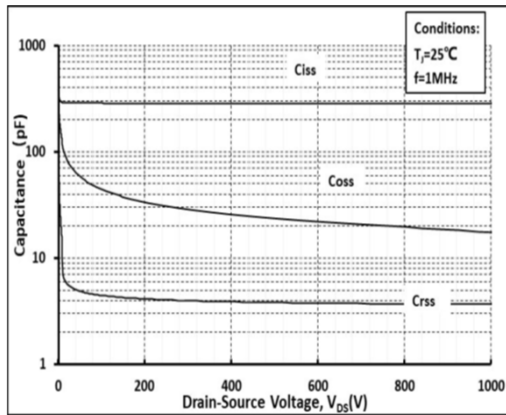


Fig 16: Safe Operating Area

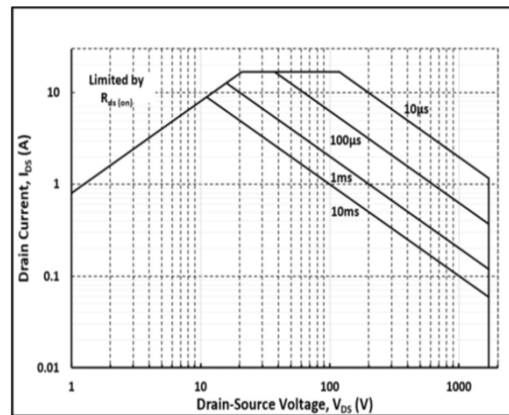
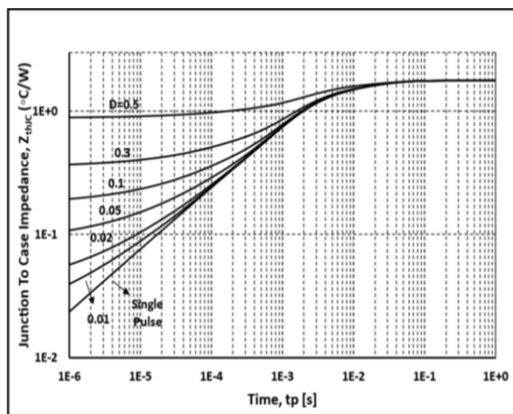


Fig 17: Transient Thermal Impedance





Test Circuit & Waveform

Figure A. Definition of switching times

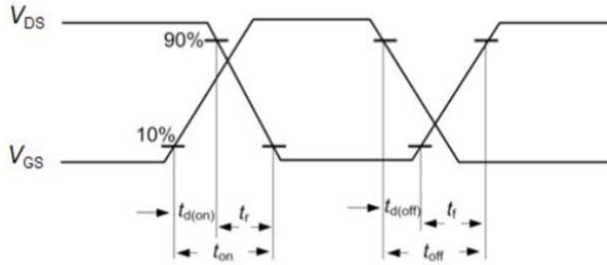


Figure B. Dynamic test circuit

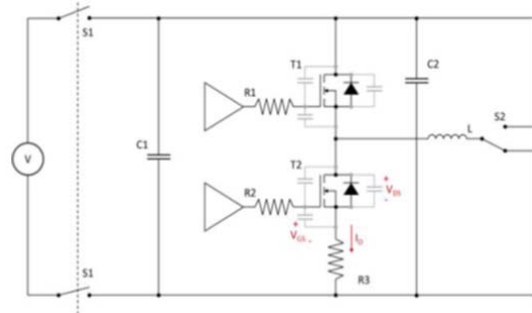


Figure C. Definition of body diodeswitching characteristics

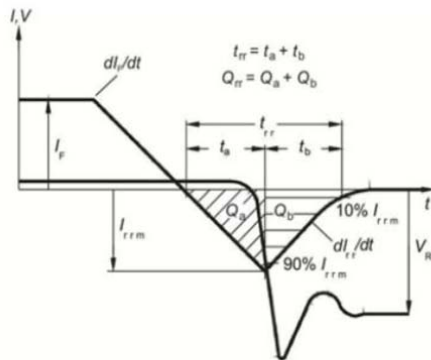
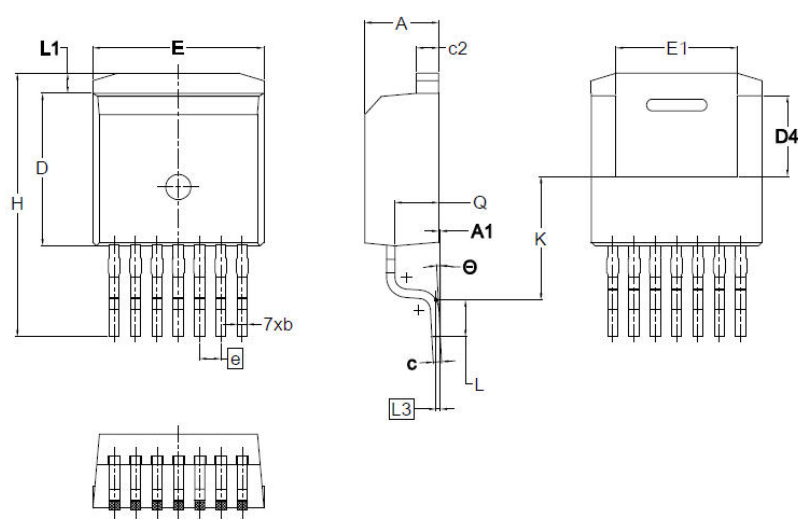


Figure C. Definition of diode switching characteristics



Package Dimensions

Package TO-263-7L



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.30	4.40	4.50
A1	0.00	0.10	0.25
b	0.50	0.60	0.70
c	0.45	0.50	0.60
c2	1.20	1.30	1.40
D	8.93	9.08	9.23
D4	4.65	4.80	4.95
E	10.08	10.18	10.28
E1	6.82	7.22	7.62
e	1.27 BSC		
H	15.00	15.70	16.00
K	7.30		
L	1.90	2.20	2.50
L1	1.00	1.20	1.40
L3	0.25 BSC		
Q	2.45	2.60	2.75
Θ	0°	3°	7°



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